

RoHS

COMPLIANT HALOGEN

Available

### 4998W-VB Datasheet

### Dual N-Channel 100-V (D-S) MOSFET

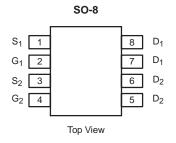
PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)			
100	0.063 at V <sub>GS</sub> = 10 V	5.8	9 nC			
	0.084 at $V_{GS}$ = 6 V	4.8	9110			

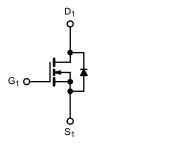
#### FEATURES

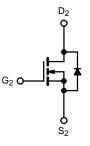
- Halogen-free According to IEC 61249-2-21
   Available
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % UIS Tested

#### **APPLICATIONS**

- High Frequency Boost Converter
- LED Backlight for LCD TV







N-Channel MOSFET

N-Channel MOSFET

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	100	V
Gate-Source Voltage		V <sub>GS</sub>	± 20	v
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C T <sub>C</sub> = 70 °C		5.8 4.4	
	T <sub>A</sub> = 25 °C T <sub>A</sub> = 70 °C		3.4 <sup>a, b</sup> 2.5 <sup>a, b</sup>	_
Pulsed Drain Current		I <sub>DM</sub>	20	A
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C T <sub>A</sub> = 25 °C	I <sub>S</sub>	5 2.1 <sup>a, b</sup>	
Single Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	19	
Single Avalanche Energy		E <sub>AS</sub>	18	mJ
Maximum Power Dissipation	$T_{C} = 25 °C$ $T_{C} = 70 °C$ $T_{A} = 25 °C$ $T_{A} = 70 °C$	P <sub>D</sub>	5 3.2 2.5 <sup>a, b</sup> 1.6 <sup>a, b</sup>	w
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, c</sup>	$t \le 10 s$	R <sub>thJA</sub>	37	50	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	17	21	- 0/10		

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85  $^\circ\text{C/W}.$

d. T<sub>C</sub> = 25 °C.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	<u> </u>				1		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	100			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			120		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 9			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	2		4.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	I <sub>DSS</sub>	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ	
Zero Gate Voltage Drain Current		$V_{DS}$ = 100 V, $V_{GS}$ = 0 V, $T_{J}$ = 55 °C			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5$ V, $V_{GS} = 10$ V	20			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.4 A		0.063		_	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 6 V, I_{D} = 2.8 A$		0.084		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3.4 A		10		S	
Dynamic <sup>b</sup>	<u> </u>				1		
Input Capacitance	C <sub>iss</sub>			600		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		90			
Reverse Transfer Capacitance	C <sub>rss</sub>			50			
Tatal Oata Oharma	Qg	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.4 \text{ A}$		13.5	20	nC	
Total Gate Charge				9	13.5		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 50$ V, $V_{GS} = 6$ V, $I_{D} = 3.4$ A		3			
Gate-Drain Charge	Q <sub>gd</sub>			4.6			
Gate Resistance	Rg	f = 1 MHz		1		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			15	25	-	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 14.3 $\Omega$		12	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 3.5 A, $\text{V}_\text{GEN}$ = 6 V, $\text{R}_g$ = 1 $\Omega$		12	20		
Fall Time	t <sub>f</sub>			10	15		
Turn-On Delay Time	t <sub>d(on)</sub>			10	15	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 14.3 $\Omega$		12	20	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 3.5$ A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		15	25		
Fall Time	t <sub>f</sub>			10	15		
Drain-Source Body Diode Characteristic	cs						
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			5	٨	
Pulse Diode Forward Current	I <sub>SM</sub>				20	A	
Body Diode Voltage	V <sub>SD</sub>	$I_{S} = 3.5 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			45	70	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 3.5 A, dl/dt = 100 A/μs, T <sub>.1</sub> = 25 °C		80	120	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$r_F = 0.5 \text{ A}, \text{ u/ul} = 100 \text{ A/}\mu\text{s},  \text{I}_J = 25 ^{\circ}\text{C}$		33			
Reverse Recovery Rise Time	t <sub>b</sub>	1		12	1	ns	

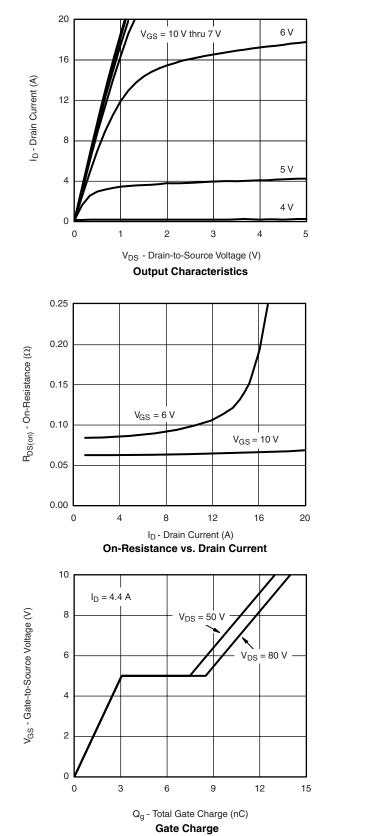
Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s$ , duty cycle  $\leq$  2 % b. Guaranteed by design, not subject to production testing.

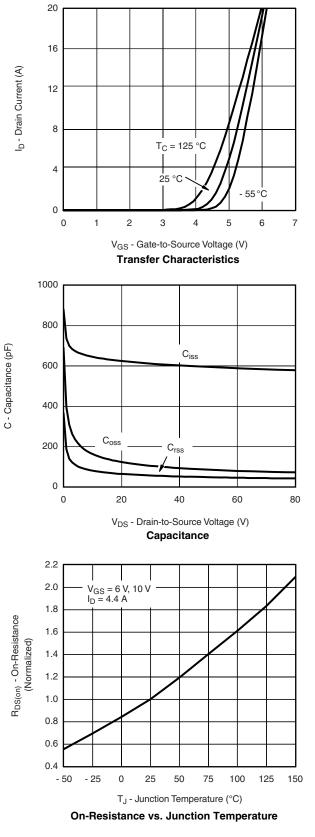
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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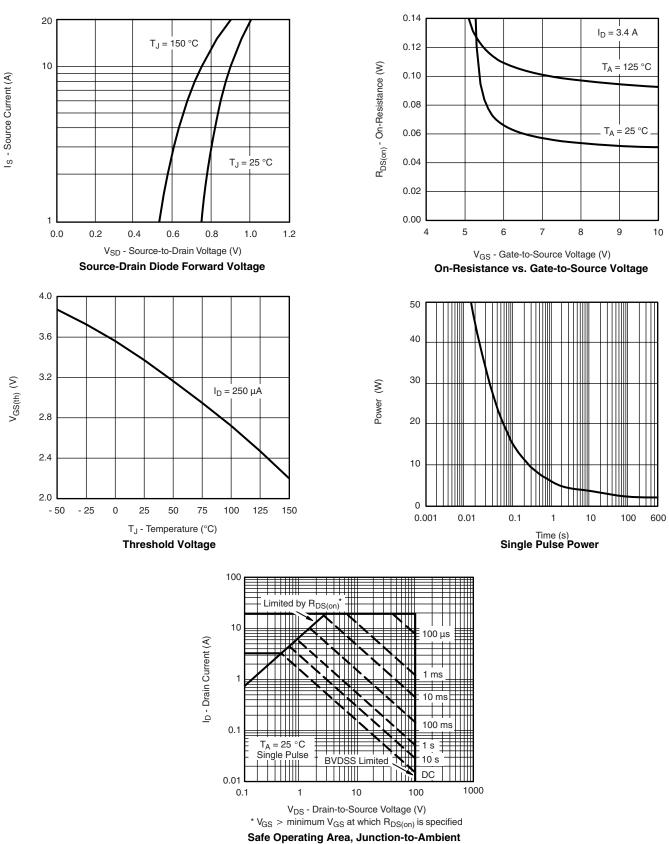


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

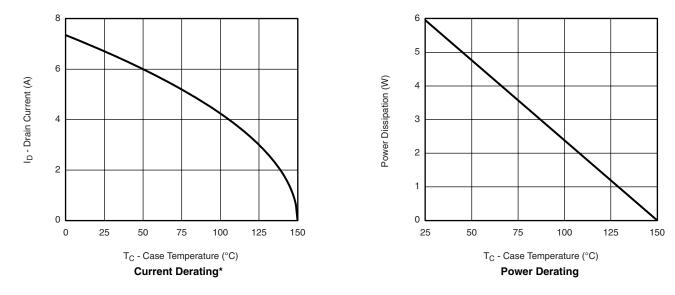




#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







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\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

2

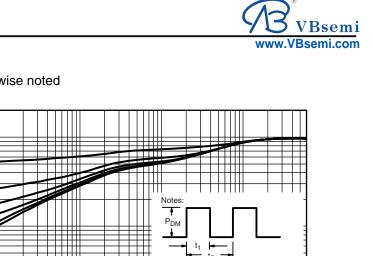
1

0.1

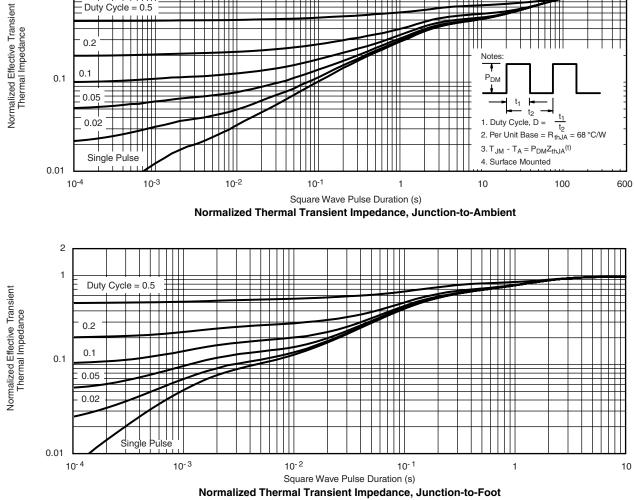
Duty Cycle = 0.5

0.2

0.1



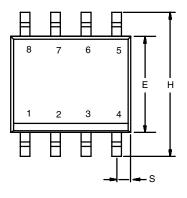
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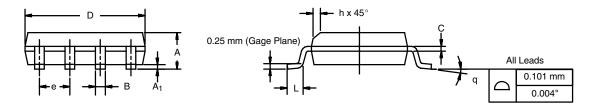






# SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

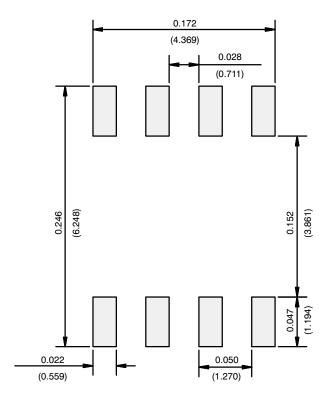




	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



**RECOMMENDED MINIMUM PADS FOR SO-8** 



Recommended Minimum Pads Dimensions in Inches/(mm)



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